



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A1405-01** DATE: **June 23, 2014**
Product Affected: PBGA-208 & PBGA-256
(Refer to affected part list in Attachment 2)

Date Effective: **September 23, 2014**

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☐ Product Mark
☒ Back Mark Lot# will have a "Y" suffix
☐ Date Code
☐ Other

Contact: IDT PCN DESK

Attachment: ☒ Yes ☐ No

E-mail: pcndesk@idt.com

Samples: Please contact your local sales representative for sample request & availability.

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
☐ Wafer Fabrication Process
☐ Assembly Process
☐ Equipment
☒ Material
☐ Testing
☐ Manufacturing Site
☐ Data Sheet
☐ Other

This notification is to advise our customers that IDT has successfully completed the qualification of Copper Wire Bonding at Amkor, Philippines assembly facility for the packages listed above.

There is no change in the moisture sensitivity performance.

Please refer to the following attachments for additional information.
Attachment 1 outlines the qualification results.
Attachment 2 shows the affected part numbers.

RELIABILITY/QUALIFICATION SUMMARY:

There is no expected change to the product quality or reliability performance.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 90 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____

☐ **Approval for shipments prior to effective date.**

Name/Date: _____

E-Mail Address: _____

Title: _____

Phone# /Fax# : _____

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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ATTACHMENT 1 - PCN # : A1405-01

PCN Type: Assembly Material Change - Gold Wire to Copper Wire

Data Sheet Change: None

Details Of Change:

This notification is to advise our customers that IDT has successfully completed the qualification of Copper Wire Bonding at Amkor, Philippines assembly facility for the packages listed in page 1.

There is no change to the moisture performance of these packages.

Customers may expect to receive shipments with Copper wire process no sooner than 90 days from the date of this notification, June 23, 2014. Product assembled with Gold wire and Copper wire will be shipped during the transition period or until the Gold wire inventory has been depleted. However please note that product assembled with Gold wire and Copper wire will not be mixed in one tray stack, or tape and reel.

We request you to acknowledge receipt of this notification within 30 days of the date of this PCN notification. If you require samples to conduct an evaluation, please make your sample request within 30 days as samples are not built ahead of the change for all device options. You may contact your local sales representative to acknowledge this PCN and request samples.

Assembly Material : There is no change in the mold compound and die attach materials. The material sets used in assembly is in compliance with RoHS 5 (standard products) and RoHS 6 (green products) requirement.
There is no change in the moisture sensitivity performance.

Sample Availability : Samples are not built ahead of the change for all device types and may not be available for all affected device types.
Please contact your local IDT sales representative for your sample request and availability.



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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT 1 - PCN # : A1405-01

Qualification Test Result :

Qual Vehicle: PBGA-672 (3 lots)

Test Description	Test Method	Test Results (SS / Rej)
* High Accelerated Stress Test (Biased, 130 °C/85% RH, 96 Hrs)	JESD22-A110	77/0, 77/0, 77/0
* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)	JESD22-A104	77/0, 77/0, 77/0
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	77/0, 77/0, 77/0

Note:

* Test requires moisture pre-conditioning sequence per JESD22-A113C and will use the existing moisture sensitivity level that has been qualified for this material set.

2. Product Electrical Characterization

Product electrical characterization has been successfully completed on representative product families and copper wire performance was comparable to gold wire performance.



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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT 2 - PCN # : A1405-01

Affected Part Numbers

Part Number	Part Number	Part Number	Part Number
82P2284BB	82P2588BBG	82P5088BBG	82V2088BB
82P2284BB8	82P2588BBG8	82P5088BBG8	82V2088BBG
82P2284BBG	82P5048BB	82P9734BB	82V2604BB
82P2284BBG8	82P5048BB8	82P9734BB8	82V2604BBG
82P2288BB	82P5048BBG	82P9734BBG	82V2608BB
82P2288BB8	82P5048BBG8	82P9734BBG8	82V2608BBG
82P2288BBG	82P5058BB	82P9738BB	82V9638BB
82P2288BBG8	82P5058BB8	82P9738BB8	82V9638BB8
82P2294BBG	82P5058BBG	82P9738BBG	82V9638BBG
82P2294BBG8	82P5058BBG8	82P9738BBG8	82V9638BBG8
82P2588BB	82P5088BB	82V2048EBB	
82P2588BB8	82P5088BB8	82V2048EBBG	